

Semico Fab Database Update Summary First Half 2017

June 2017

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Below are the column headings included in the Excel workbook accompanying this Word document. There are over 900 rows in the workbook:

Status	Current Process Tech (nm)
Company	Capacity (wpm) 2008
FabName	Capacity (wpm) 2009
Wafer Size (mm)	Capacity (wpm) 2010
Region	Capacity (wpm) 2011
Country	Capacity (wpm) 2012
City	Capacity (wpm) 2013
State/Region	Capacity (wpm) 2014
Special Substrate	Capacity (wpm) 2015
University	Capacity (wpm) 2016
Development	Capacity (wpm) 2017
IDM	Full Capacity (w/mo)
Foundry	Construction Start
Process Type	Initial Prod Yr
Products	Vol Prod Yr
Logic	Most Recent
ASSPs	Expansion/Construction Date
ASICs	Yr Closed or Closing
Analog	Empl
Discretes	Total Capex (millions)
Passives	Site Size
Opto	Total Fab Size (K sq. m)
DRAM	Cleanroom Size (K sq. m)
Mobile RAM	
SRAM	
NAND - 2D	
NAND - 3D	
XPoint	
NOR	
Other NV Memory	
MEMS	
Image Sensors	
Oth Sensors	
LED	
LED Drivers	
LCD Drivers	
Other	
Bipolar	